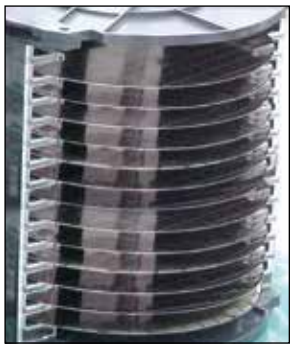
300 mm Wafer Processing

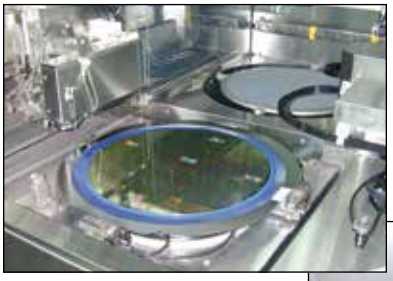
Amkor 300 mm Wafer Handling Capabilities

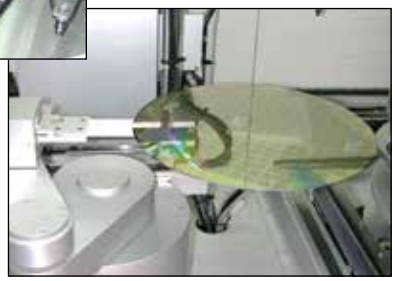


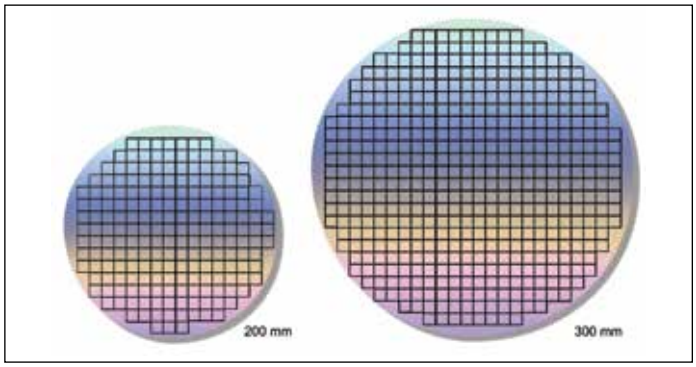
The industry's transition to 300 mm wafer technology is in full swing. Amkor has established capability to support the unique and challenging needs of handling and processing of 12 inch wafers. Chip manufacturers demand the highest levels of sophistication in the tools used for wafer handling, transport and storage. Amkor now has fully qualified production assembly capability for flip chip, WLCSP and wire bond products in place for handling 300 mm wafers in several of our factories worldwide. Future expansion of 300 mm capability will be made as necessary to meet the growing demands of the market.

Amkor offers high volume electroplated wafer solder bumping for 300 mm wafers, including low alpha, high lead, eutectic, and lead free in our Taiwan facility. Amkor has rapidly expanded our 300 mm bumping production capacity to meet the growing "turnkey" flip chip business model which includes bumped wafer probe, assembly, and test.

Amkor also offers turnkey services for high volume 300 mm WLCSP production. These services facilitate the entire process from unbumped wafers to the shipment of tested die in tape and reel.







The 300 mm wafer has 225% more usable area of silicon.

Photo courtesy of Datacon

300 mm Qualified Tooling

- Wafer bump
- Wafer shipper – Unpacker/packer
- Wafer mount to dicing frame
- Wafer saw
- Wafer map
- Wafer probe
- Backside grind taper
- Backside grind
- Backside grind detaper
- Measurement tools
- Automated defect inspection
- Die attach
- Flip chip attach
- Laser mark
- Tape and reel

Specific 300 mm handling capabilities may vary by factory location.

Visit Amkor Technology online for locations and to view the most current product information.

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